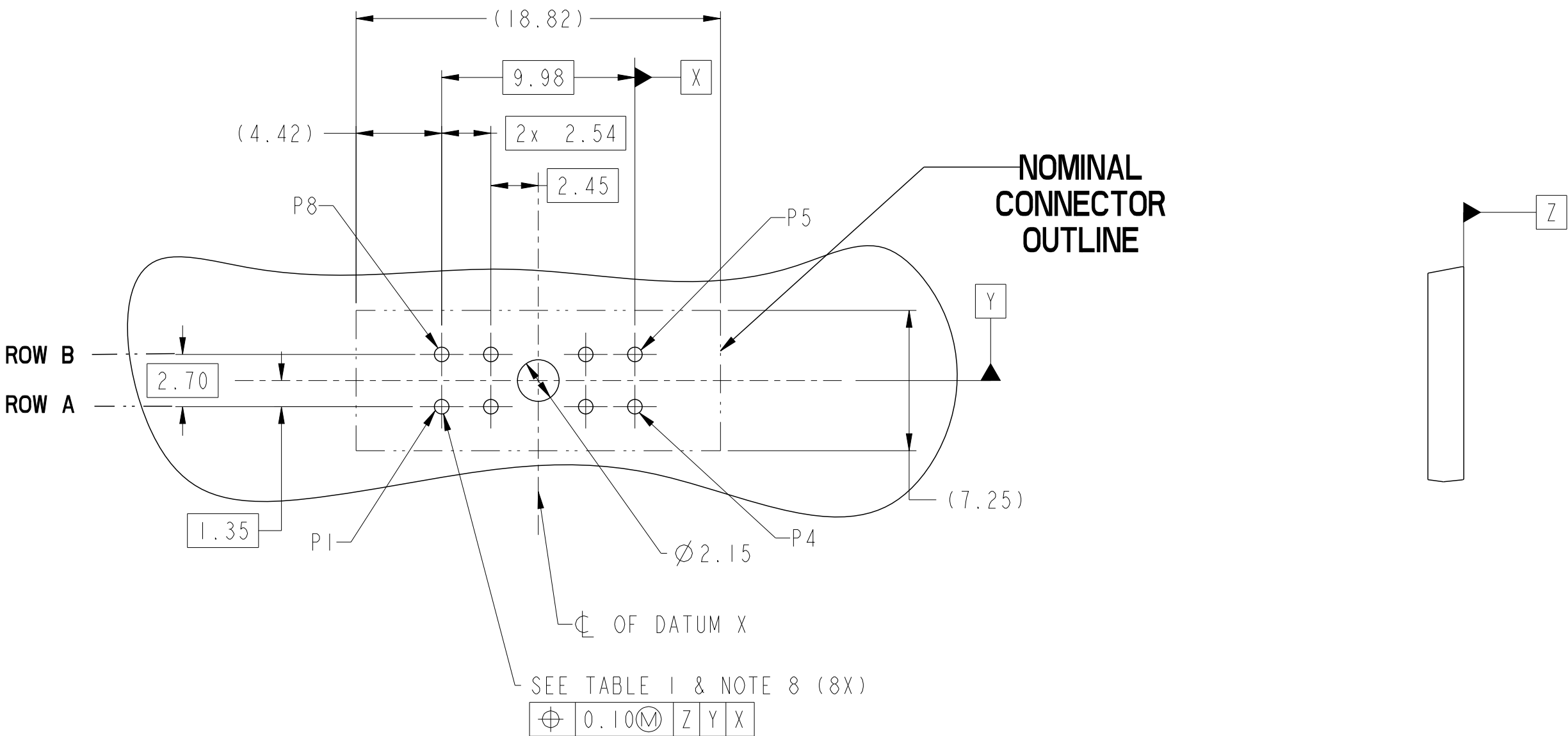
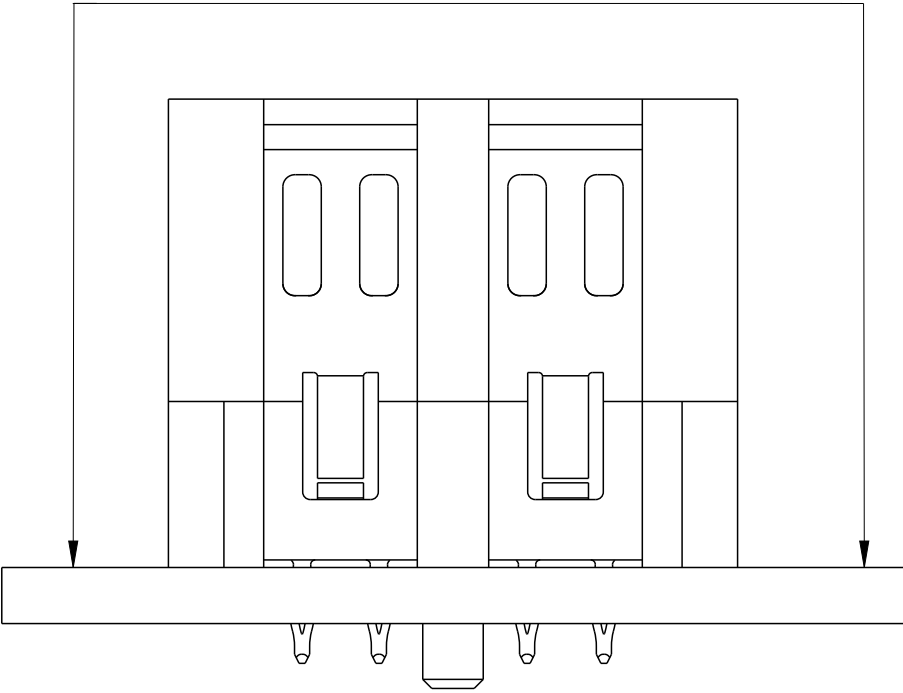




RECOMMENDED PCB LAYOUT
VIEWED FROM CONNECTOR SIDE



spec ref -				dr Hai-Ling Liu 2016/04/13		projection 	mm 	size A2	scale 2:1
tolerance std		TOLERANCES UNLESS OTHERWISE SPECIFIED		eng Hai-Ling Liu 2016/05/05				ecn no -	
ISO 406 ISO 1101				chr Terris Liu 2016/05/04				rel level Released	
		appr Pei-Ming Zheng 2016/05/05		product family -					
surface -		linear	0.X ±0.5	Amphenol FCI	title HPCE MEZZANINE 4LP WITH RIB		dwg no 10139324	rev A	
✓			0.XX ±0.25						
			0.XXX ±0.10						
ASME Y14.5		angular 0° ±2°		cat. no. -		Product - Customer Drw		sheet 2 of 3	

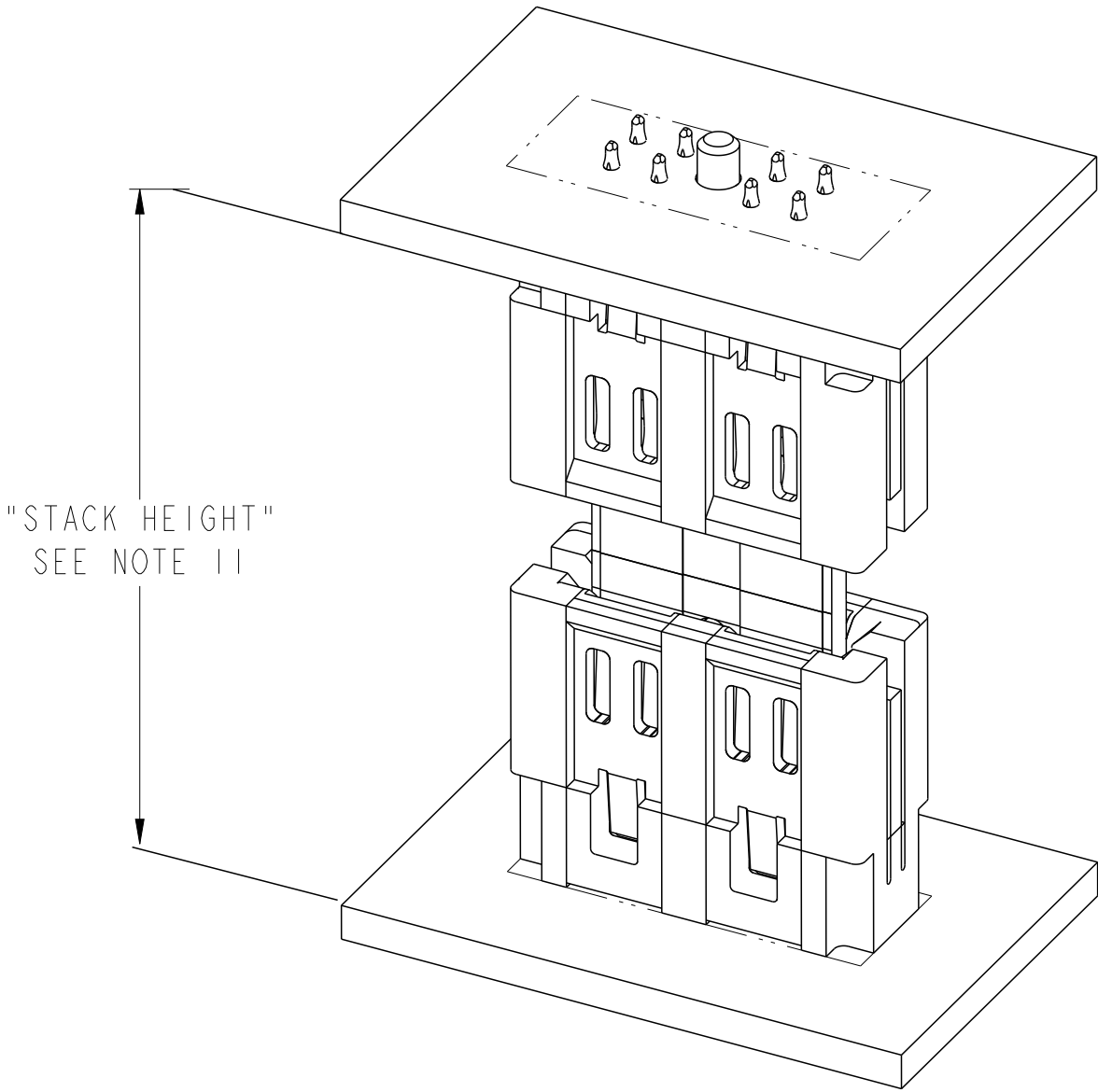
CONTACT TYPE	TOP LAYER DESCRIPTION	TABLE I (HPCE / PRESS-FIT TAILS) PLATED THROUGH-HOLE REQUIREMENTS				
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	TIN THICKNESS	FINISHED HOLE DIAMETER
POWER	TIN-LEAD	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	0.005 - 0.015	--	0.65 - 0.80
	IMMERSION TIN	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	0.9 - 1.5um	0.70 - 0.80
	COPPER (SEE NOTE 8)	0.81-0.86 (0.85 DRILL)	0.025 - 0.050	--	--	0.70 - 0.80
CONTACT TYPE	TOP LAYER DESCRIPTION	TABLE I (HPCE / SOLDER TAILS) PLATED THROUGH-HOLE REQUIREMENTS				
		DRILLED HOLE DIAMETER	COPPER THICKNESS	TIN-LEAD THICKNESS	TIN THICKNESS	FINISHED HOLE DIAMETER
POWER	TIN-LEAD	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	0.005 - 0.015	--	0.94 - 1.10
	IMMERSION TIN	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	--	0.9 - 1.5um	0.94 - 1.10
	COPPER (SEE NOTE 8)	1.10-1.16 (1.15 DRILL)	0.025 - 0.050	--	--	0.94 - 1.10

NOTES:

1. CONNECTOR MATERIALS:

HOUSING: HIGH TEMPERATURE THERMAL PLASTIC, BLACK
UL 94V-0 COMPLIANT

CONTACTS: HIGH PERFORMANCE COPPER ALLOY.
2. CONTACT FINISH REF. GS-12-1261 SECTION 5.3.
3. PRODUCT SPECIFICATION: GS-12-1261.
4. APPLICATION SPECIFICATION: GS-20-128.
5. PRODUCT MARKING ON HOUSING IN AREA SHOWN SHOULD MEET AFCI SPECIFICATION GS-24-007.
6. PACKAGING MEETS FCI SPECIFICATION GS-14-937.
7. HOUSING COMPONENT WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR 60 SECONDS IN A CONVECTION, INFRA-RED, OR VAPOR PHASE REFLOW OVEN.
8. COPPER PLATING THICKNESS IN CENTER OF VIA-HOLE CAN BE NO MORE THAN 0.003 LESS THAN OTHER AREAS.
9. ALL HOLE SIZES ARE FINISHED HOLE SIZES.
10. INTENDED USE: TWO ASSEMBLIES (P/N 10134991 MATE TO 10136109) MEZZANINE STACKED USING PCB TO CONTROL STACK HEIGHT.
DIM "L" + 10.98mm = FINAL MEZZANINE STACK HEIGHT.
DIM "L" RANGES FROM 21.02-46.62 mm .
11. SEE DRAWING 10135823 FOR MATING PCB DETAIL



spec ref -			dr Hai-Ling Liu		2016/04/13		projection	mm	size A2	scale 1:1				
tolerance std		eng Hai-Ling Liu		2016/05/05		ecn no -			rel level Released					
ISO 406		chr Terris Liu		2016/05/04										
ISO 1101		appr Pei-Ming Zheng		2016/05/05										
TOLERANCES UNLESS OTHERWISE SPECIFIED			product family -											
surface	linear	0.X	±0.5	Amphenol FCI	title	HPCE MEZZANINE			dwg no	10139324	rev A			
		0.XX	±0.25											
		0.XXX	±0.10											
	ASME Y14.5	angular	0°			±2°	cat. no.	-				Product - Customer Drw		sheet 3 of 3